

Japan Packaging Committee Meeting Summary and Minutes

SEMI Japan Standards Fall 2013 Meetings
Monday, November 11, 2013, 15:00-17:00
SEMI Japan, Tokyo, Japan

Next Committee Meeting

SEMI Japan Standards Spring 2014 Meetings
Thursday, March 20, 2014, 15:00-17:00
SEMI Japan, Tokyo, Japan

Table 1 Meeting Attendees

Co-Chairs: Kazunori Kato (AiT), Yutaka Koma (Consultant), Masahiro Tsuruya (iNEMI)

SEMI Staff: Naoko Tejima (SEMI Japan)

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
Tokyo Seimitsu	Chiba	Kiyotaka	Disco	Nakanishi	Yuji
AiT	Kato	Kazunori	AIST	Shimamoto	Haruo
AET	Kiyono	Mikio	Micron	Sonobe	Kaoru
Consultant	Koma	Yutaka	iNEMI	Tsuruya	Masahiro
Disco	Masuchi	Sumio	SEMI Japan	Tejima	Naoko
Lintec	Murakami	Yukinori			

** alphabetical order by last name*

Table 2 Leadership Changes

<i>Group</i>	<i>Previous Leader</i>	<i>New Leader</i>
3D-IC Study Group	Masahiro Tsuruya (iNEMI) Kazunori Kato (AiT) Yutaka Koma (Consultant)	Masahiro Tsuruya (iNEMI) Haruo Shimamoto (AIST)

Table 3 Ballot Results

Passed ballots and line items will be forwarded to the ISC Audit & Review Subcommittee for procedural review.

Failed ballots and line items were returned to the originating task forces for re-work and re-balloting.

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
5637	Revision of SEMI G95-0613, Mechanical Interface Specification for 450mm Load Port for Tape Frame Cassettes in the Backend Process	Passed with editorial changes

Table 4 Authorized Ballots

<i>Document #</i>	<i>When</i>	<i>SC/TF/WG</i>	<i>Details</i>
5636	Cycle 1, 2014	JA 450mm Assembly and Test Die Preparation Task Force	Revision of SEMI G92-0412, Specification for Tape Frame Cassette for 450mm Wafer

Table 5 Authorized Activities

None.

Table 6 New Action Items (or move to Section 8, Action Item Review)

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
PKG120829-2	Committee Co-Chairs	To review the Committee Charter of Japan Packaging Committee.
PKG130325-2	3D-IC Study Group	To discuss the contents of SJ2013 Pavilion and Workshop with SEMI Staff.
PKG130325-3	SEMI	To publish G92 Related Information.
PKG130719-6	SEMI	To check whether there are some documents for 5-year-review procedure.
PKG130719-9	Co-chairs	To review all SNARFs and check whether they are written in the right way.
PKG131111-1	SEMI staff	To check the concrete contents of “new activity on unsupported thin wafer handling” to TF.
PKG131111-2	SEMI staff	To get the presentation materials of SEMATECH and to distribute it to JA PKG TC members.
PKG131111-3	SEMI staff	To raise an issue to SPI TF that the respond to reject-voters is different by each region.
PKG131111-4	SEMI staff	To forward adjudication result of Doc.#5637 to the ISC A&R Subcommittee for procedural review.
PKG131111-5	450mm ATDP Task Force	To submit Doc.#5636 for Cycle 1, 2014.
PKG131111-6	SEMI staff	To get some information and materials of MEMS Wafer Bonded TF / MEMS Packaging TF and to distribute it to JA PKG TC members.
PKG131111-7	Kazunori Kato	To convene an ad-hoc co-leaders meeting to review the Committee Charter and all SNARFs, and check whether they are written in the right way of Japan Packaging Committee. (Participants: Kasunori Kato, Yutaka Koma, Masahiro Tsuruya, Nobuo Hayasaka and Haruo Tabata)
PKG131111-8	SEMI staff	To send the list of the documents for 5-year-review procedure to Co-chairs.

1 Welcome, Reminders and Introductions

Masahiro Tsuruya, committee co-chair, called the meeting to order at 15:00. Self-introductions were made followed by the agenda review.

2 Required Meeting Elements

The meeting reminders on program membership requirement, antitrust issues, intellectual property issues and international effective meeting guidelines, were reviewed by SEMI staff, Naoko Tejima.

3 Review of Previous Meeting Minutes

The committee reviewed the minutes of the previous meeting held on July 19, 2013.

Motion: To approve the minutes of the previous meeting as written.

By / 2nd: Kazunori Kato (AiT) / Yutaka Koma (Consultant)

Discussion: None

Vote: 8 in favor and 0 opposed. **Motion passed.**

Attachment: 01_JA_Packaging_Previous_Mtg_Minutes_131111

4 SEMI Staff Report

Naoko Tejima gave the SEMI staff report. This report included SEMI Global 2013 Calendar of Events, Global Standards Meeting Schedule, SEMICON Europa Standard Meeting Schedule, NA Standards Fall 2013 Meetings, 2013 Critical Dates for SEMI Standards Ballots, SEMI Standards Publication, SEMICON Japan 2013 Information and Contact Information.

Attachment: 02_SEMI_Staff_Report_131111

5 Liaison Reports

5.1 North America 3DS-IC Committee Report

Naoko Tejima briefly reported for the North America 3DS-IC Committee. This report included Leadership, Organization Chart, Meeting Information, SNARFs, Document Review Summary, Task Force Updates, Upcoming NA 3DS-IC Ballots, NA 3DS-IC Spring 2014 Meeting Schedule and Contact information. Of note:

- What is “new activity on unsupported thin wafer handling” of Thin Wafer Handling TF?

Action Item: SEMI staff to check the concrete contents of “new activity on unsupported thin wafer handling” to TF..

Action Item: SEMI staff to get the presentation materials of SEMATECH and to distribute it to JA PKG TC members.

Attachment: 03_NA_3DS-IC_Comm_Report_131111

5.2 Taiwan 3DS-IC Committee Report

Naoko Tejima briefly reported for the Taiwan 3DS-IC Committee. This report included Organization Chart, Task Force Overview, SNARFs, New Activity, Meeting Information, and Contact Information. Of note:

- Some of JA 3D-IC Study Group (SG) members voted to reject for Document #5473, “New Standard: Guide for Alignment Mark for 3DS-IC Process”. However, it was passed committee review at TW 3DS-IC Committee meeting without any feedbacks to the reject-voters. Even if it was the due process, its feedbacks should be sent to reject-voters.

Action Item: SEMI staff to raise an issue to SPI TF that the respond to reject-voters is different by each region.

Attachment: 04_TW_3DS-IC_Comm_Report_131111

6 Ballot Review

6.1 Doc.5637, Revision of SEMI G95-0613, Mechanical Interface Specification for 450mm Load Port for Tape Frame Cassettes in the Backend Process

This document passed committee review with editorial changes and will be forwarded to the ISC A&R SC for procedural review.

Missing of the indicator parts of "Figure 1" was pointed out by the one of the voters as "Accept with Comment". Since this is due to a clerical error of SEMI staff and these indicators are mentioned in "Table 1" of this document, the JA Packaging Committee decided that these should be corrected as the editorial changes.

Action Item: SEMI staff to forward adjudication result of Doc.#5637 to the ISC A&R Subcommittee for procedural review.

Attachment: 05_Ballot_Report_for_5637_131111

7 Task Force Reports

7.1 Japan Regional Standards Committee (JRSC)

Kazunori Kato reported for the Japan Regional Standards Committee (JRSC) that there were no particular things should be reported.

7.2 Electromagnetic Characterization Study Group

Mikio Kiyono reported for the Electromagnetic Characterization Study Group. Of note:

- JEITA has issued the standards about LPB (LSI Package and Board) design workflow, and plans to issue as international standards through IEEE, IEC or ISO at the same time as disseminate it actively.
- SG is working with the JEITA LPB WG leader to be held Tutorial Seminar or Symposium about this standards in the next spring.

Attachment: 06_ElectromagneticCharacterization_SG_Report_131111

7.3 Packages and Packaging Materials Eco-efficiency Task Force

No report was provided by the Task Force.

7.4 Wafer Shipping Container for Assembly & Packaging Task Force

Naoko Tejima gave the report from Kazuhiko Nakamura, the leader of the Wafer Shipping Container for Assembly & Packaging Task Force.

Attachment: 07_WaferShippingContainer_TF_Report_131111

7.5 DFM Study Group

No report was provided by the Task Force.

7.6 450mm Japan Assembly & Test Die Preparation Task Force

Sumio Masuchi reported on progress for 450mm Japan Assembly & Test Die Preparation Task Force.

TF is drafting the document of *Doc.#5636, "Revision of SEMI G92-0412, Specification for Tape Frame Cassette for 450mm Wafer"* and it will be submitted for Cycle 1, 2014. It was presented to the committee for approval.

Motion: To submit Doc.#5636 for Cycle 1 2014. (Inter-Committee Ballot to PI&C Committee.)

By / 2nd: Sumio Masuchi (Disco) / Kazunori Kato (AiT)

Discussion: None.

Vote: 9 in favor and 0 opposed. **Motion passed.**

Action Item: 450mm ATDP Task Force to submit Doc.#5636 for Cycle 1, 2014.

7.7 Thin Die Bending Strength Measurement Method Task Force

Haruo Shimamoto reported on progress for the Thin Chip Die Bending Strength Measurement Method Task Force.

It was proposed that the TF should exchange the opinions with not only NA members but also Taiwan members about the contents of the document before it will be submitted to the ballot from the one of the attendees.

Attachment: 08_ThinDieBending_TF_Report_131111

7.8 3D-IC Study Group

Masahiro Tsuruya reported on progress for the 3D-IC Study Group. Of note:

- Group is coordinating the booth and the seminar during SEMICON Japan 2013 and their contents was explained.
- Kazunori Kato (AiT) and Yutaka Koma (Consultant) stepped down as a co-leader of the *3D-IC Study Group*. Haruo Shimamoto (AIST) has been appointed as a new co-leader. Masahiro Tsuruya (iNEMI) currently remains as a co-leader.
- Some of JA 3D-IC Study Group (SG) members voted to reject for Document #5473, "New Standard: Guide for Alignment Mark for 3DS-IC Process". However, it was passed committee review at TW 3DS-IC Committee meeting without any feedbacks to the reject-voters. Even if it was the due process, its feedbacks should be sent to reject-voters.

Attachment: 09_3D-IC_SG_Report_131111

7.9 Fiducial Mark Interoperability Task Force

Sumio Masuchi reported on progress for *Fiducial Mark Interoperability Task Force*. Of note:

- Standardization of fiducial mark as the alternative to the notch is now under development at the International 450mm Wafer Task Force under the Global Silicon Wafer Committee
- In order to address cross disciplinary challenge, this Task Force is established under five Global Technical Committees, and develops the Standards to support the fiducial mark.
- In the Task Force, they are listing up the items which each technical committees thinks should be standardized
- Members: H. Tsunobuchi, KEYENCE (Traceability Committee), T. Nakai, SUMCO (Silicon Wafer Committee), S. Mashiro, Tokyo Electron (Physical Interface and Carrier Committee), S. Masuchi, DISCO (Assembly and Package Committee), M. Matsuda, Hitachi Kokusai (Information and Control Committee)
- The kick off Task Force meeting will be held on December 3.

Attachment: 10_Fiducial_Mark_Interoperability_TF_Report_131111

8 Old Business

8.1 Previous Meeting Action Items

Naoko Tejima reviewed the previous meeting action items.

Table 7 Previous Meeting Actions Items

Item #	Assigned to	Details
PKG120829-2	Committee Co-Chairs	To review the Committee Charter of Japan Packaging Committee Open
PKG120829-3	All Task Force Leaders	To review the both TFOF (Charter, Scope and Members) and SNARFs (Rationale and Scope) which they themselves are involved Closed
PKG130325-1	SEMI	To forward adjudication result of Doc.4965C to the ISC A&R Subcommittee for procedural review. Closed
PKG130325-2	3D-IC Study Group	To discuss the contents of SJ2013 Pavilion and Workshop with SEMI Staff Open
PKG130325-3	SEMI	To publish G92 Related Information Open
PKG130719-1	SEMI	To correct the previous meeting minutes. Closed
PKG130719-2	SEMI	To request the NA 3DS-IC Committee to return comments to reject-voters of Doc.#5588. Closed
PKG130719-3	SEMI	To forward the adjudication result of Related Information of SEMI G92-0412 to the ISC A&R Subcommittee for procedural review Closed
PKG130719-4	450mm ATDP Task Force	To submit Doc.#5637 (G95) for Cycle 6, 2013. Closed
PKG130719-5	SEMI	To collect the TF report from the co-leaders for this time record and to ask to submit the TF report for each meeting if no one will not attend the meeting. Closed
PKG130719-6	SEMI	To check whether there are some documents for 5-year-review procedure. Open
PKG130719-7	SEMI	To provide some information about 450mm Notch-Free Wafer at SEMICON West, if any. Closed
PKG130719-8	SEMI	To send the result of the questionnaire about 450mm Notch-Free which was implemented in June. Closed Comment from HQ: Since this survey was held by the request from G450C, the result has been kept by them. If needed, they may contact individually.
PKG130719-9	Co-chairs	To review all SNARFs and check whether they are written in the right way. Open

Action Item: Kazunori Kato to convene an ad-hoc co-leaders meeting to review the Committee Charter and all SNARFs, and check whether they are written in the right way of Japan Packaging Committee. (Participants: Kazunori Kato, Yutaka Koma, Masahiro Tsuruya, Nobuo Hayasaka and Haruo Tabata)

Action Item: SEMI staff to send the list of the documents for 5-year-review procedure to Co-chairs.

9 New Business

None



10 Action Item Review

10.1 New Action Items

Naoko Tejima reviewed the new action items. These can be found in the New Action Items table at the beginning of these minutes.

11 Next Meeting and Adjournment

The next meeting of the Japan Packaging Committee is scheduled for Thursday, March 20, 2014, 15:00-17:00, at SEMI Japan, Tokyo, Japan.



Respectfully submitted by:
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Minutes approved by:

Kazunori Kato (AiT), Co-chair	December 19, 2013
Yutaka Koma (Consultant), Co-chair	December 22, 2013
Masahiro Tsuruya (iNEMI), Co-chair	December 20, 2013

Table 8 Index of Available Attachments #1

#	<i>Title</i>
1	JA_PKG_Previous_Mtg_Minutes_131111
2	SEMI_Staff_Report_131111
3	NA_3DS-IC_Comm_Report_131111
4	TW_3DS-IC_Comm_Report_131111
5	Ballot_Report_for_5637_131111
6	ElectromagneticCharacterization_SG_Report_131111
7	WaferShippingContainer_TF_Report_131111
8	ThinDieBending_TF_Report_131111
9	3D-IC_SG_Report_131111
10	Fiducial_Mark_Interoperability_TF_Report_131111

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact Naoko Tejima at the contact information above.